Features

- Trench Power LV MOSFET Technology
- Moisture Sensitivity Level 3
- Halogen Free. “Green” Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

N-Channel MOSFET

Maximum Ratings

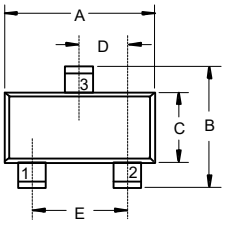
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 68.2°C/W Junction to Ambient(Note2)

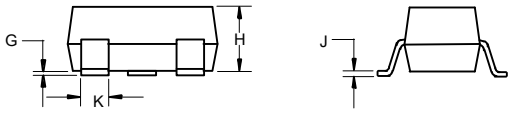
Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Volltage		V_{GS}	±20	V
Continuous Drain Current	T_A=25°C	I_D	5	A
	T_A=100°C		3.2	
Pulsed Drain Current(Note3)		I_{DM}	20	A
Total Power Dissipation(Note4)		P_D	1.8	W

Note:

1. Halogen free "Green” products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

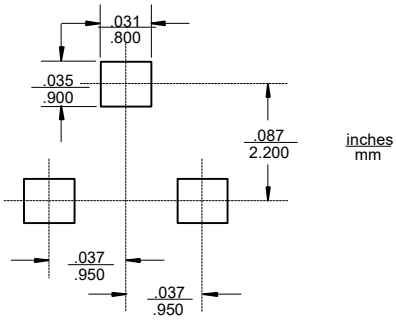
SOT-23-3L



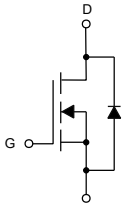


DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.113	0.117	2.87	2.97	
B	0.108	0.112	2.75	2.85	
C	0.061	0.065	1.55	1.65	
D	0.036	0.038	0.914	0.965	
E	0.073	0.077	1.85	1.95	
G	0.0016	0.0039	0.04	0.100	
H	0.041	0.045	1.05	1.15	
J	0.006	0.007	0.14	0.17	
K	0.012	0.020	0.30	0.50	

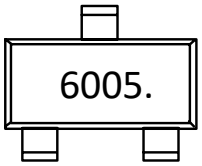
Solder Pad Layout



Internal Structure and Marking Code



1. GATE
2. SOURCE
3. DRAIN



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=250μA	60			V
Gate-Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250μA	1.0	1.5	2.5	V
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V, V_{DS}=0V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=60V, V_{GS}=0V			1	μA
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=5A		27	44	mΩ
		V_{GS}=4.5V, I_D=4A		30	49	
Gate Resistance	R_g	f=1 MHz, Open drain		2.2		Ω
Forward Transconductance	g_{fs}	V_{DS}=5V, I_D=4.5A		16		S
Diode Characteristics						
Diode Forward Current	I_S				5	A
Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_s=5A		0.8	1.2	V
Reverse Recovery Time	t_{rr}	I_F=20A,di/dt=100A/us		23		nS
Reverse Recovery Charge	Q_{rr}			20		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	V_{DS}=30V,V_{GS}=0V, f=1MHz		1175		pF
Output Capacitance	C_{oss}			64		
Reverse Transfer Capacitance	C_{rss}			54		
Total Gate Charge	Q_g	V_{DS}=30V,V_{GS}=10V,I_D=10A		23.4		nC
Gate-Source Charge	Q_{gs}			2.8		
Gate-Drain Charge	Q_{gd}			5		
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=30V,V_{GS}=10V, I_D=2A,R_G =3Ω		6.5		ns
Turn-on Rise Time	t_r			3.2		
Turn-off Delay Time	$t_{d(off)}$			26		
Turn-off Fall Time	t_f			5		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

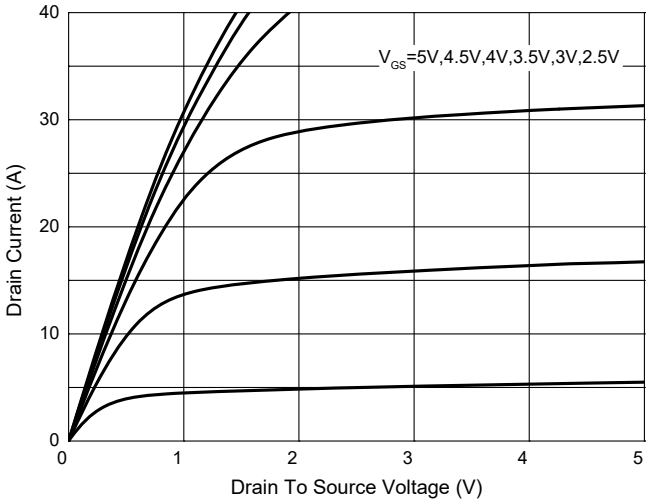


Fig. 2 - Transfer Characteristics

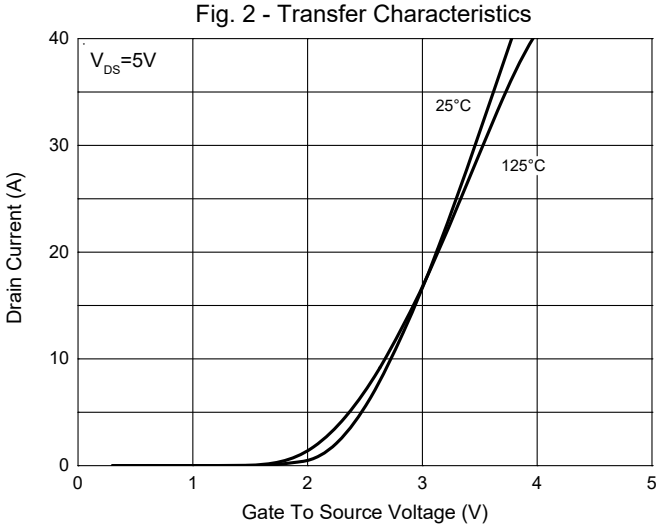


Fig. 3 - $R_{DS(ON)}$—V_{GS}

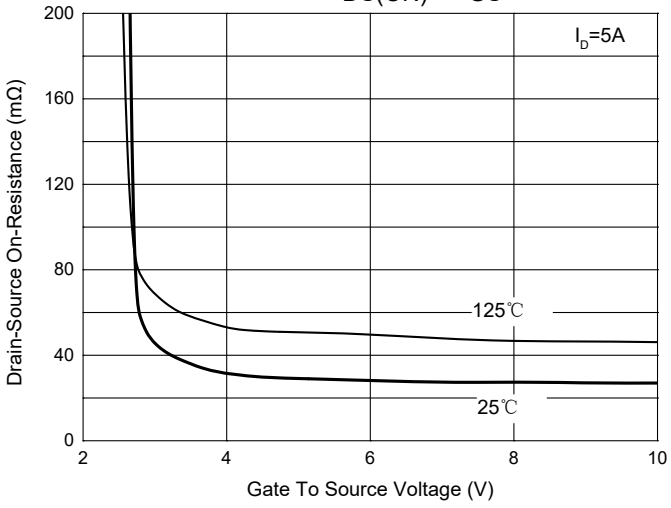


Fig. 4 - $R_{DS(ON)}$—I_D

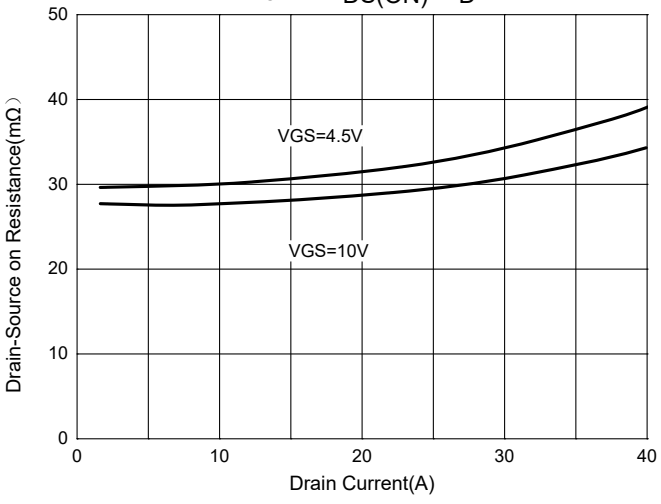


Fig. 5 - Capacitance Characteristics

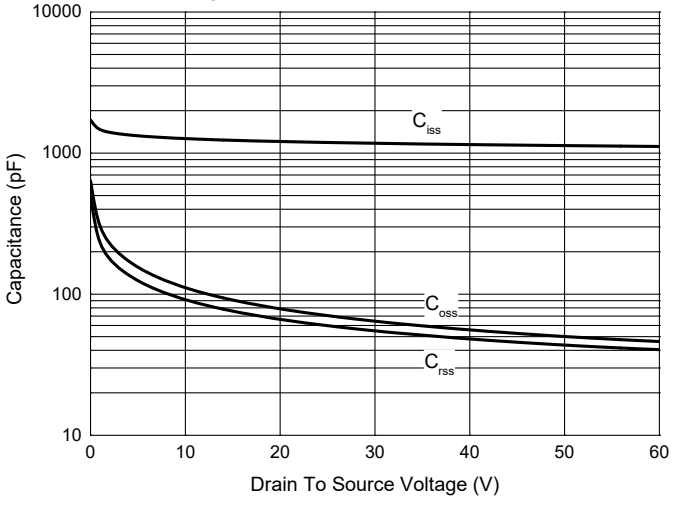
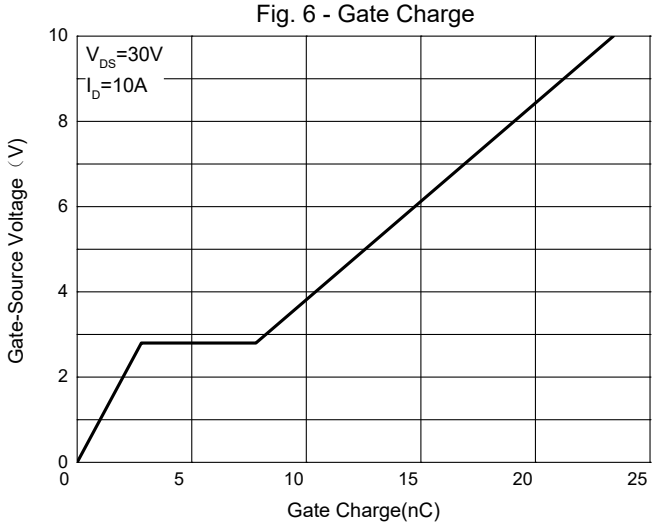


Fig. 6 - Gate Charge



Curve Characteristics

Fig. 7 - Nomalized Threshold Voltage

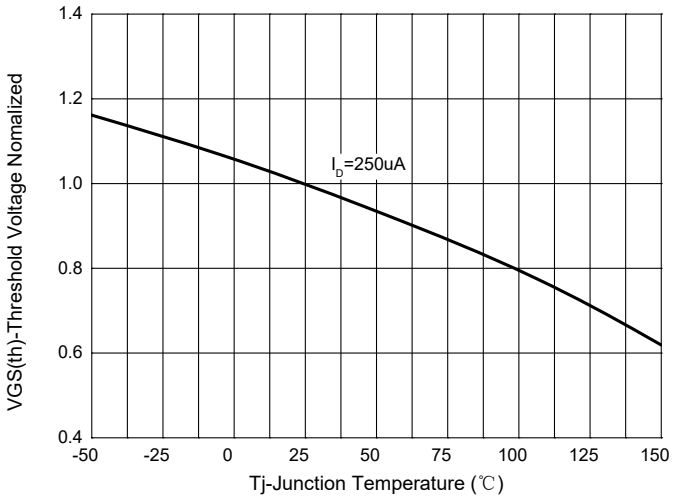


Fig.8-Normalized On Resistance Characteristics

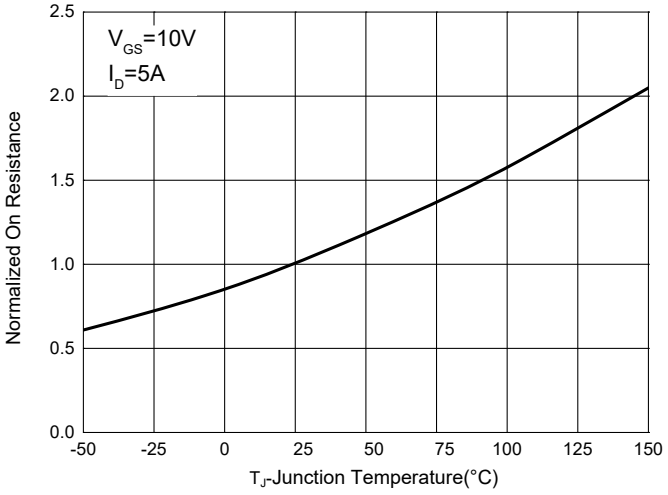


Fig.9 - I_S—V_{SD}

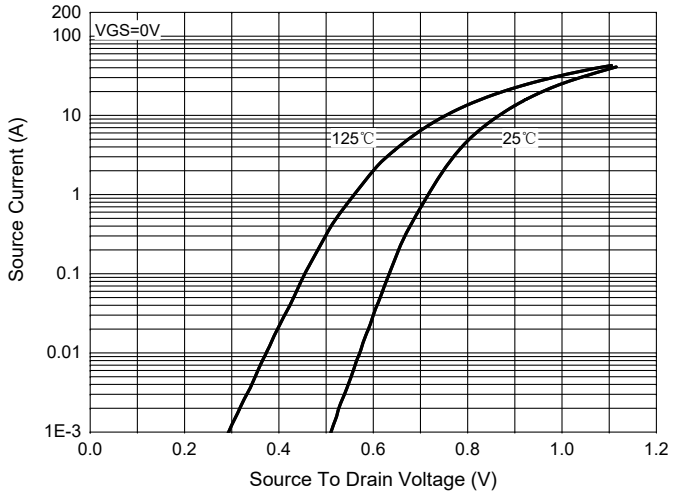


Fig. 10 - Current Current

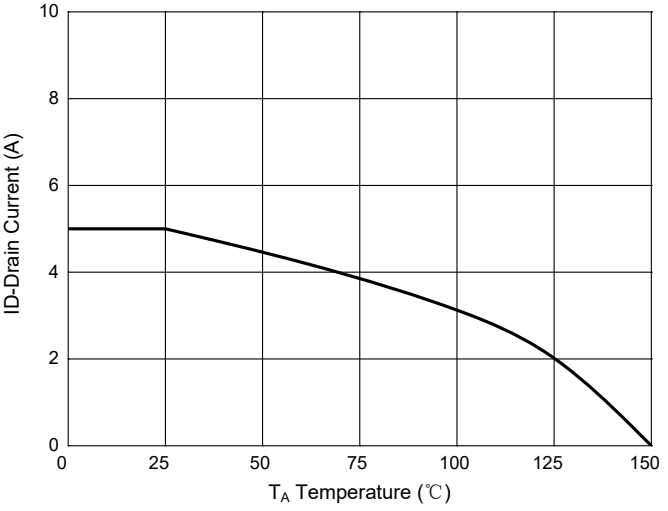
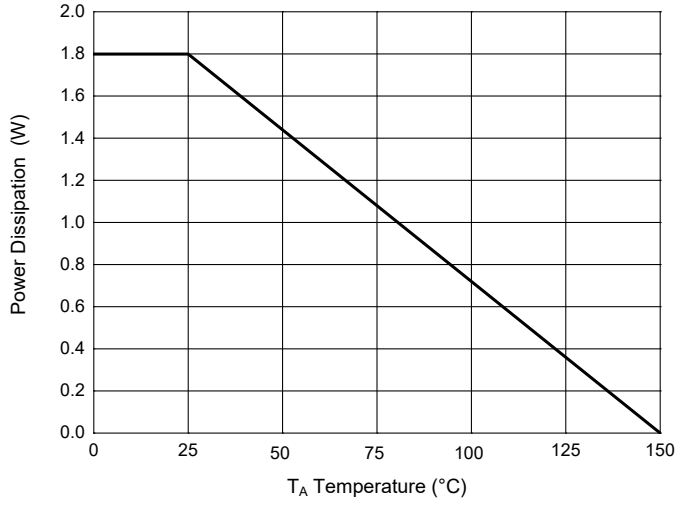


Fig.11-PD Dissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

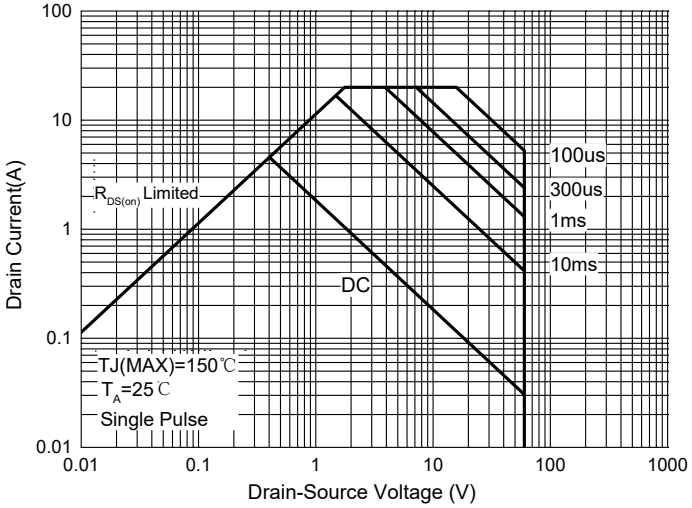
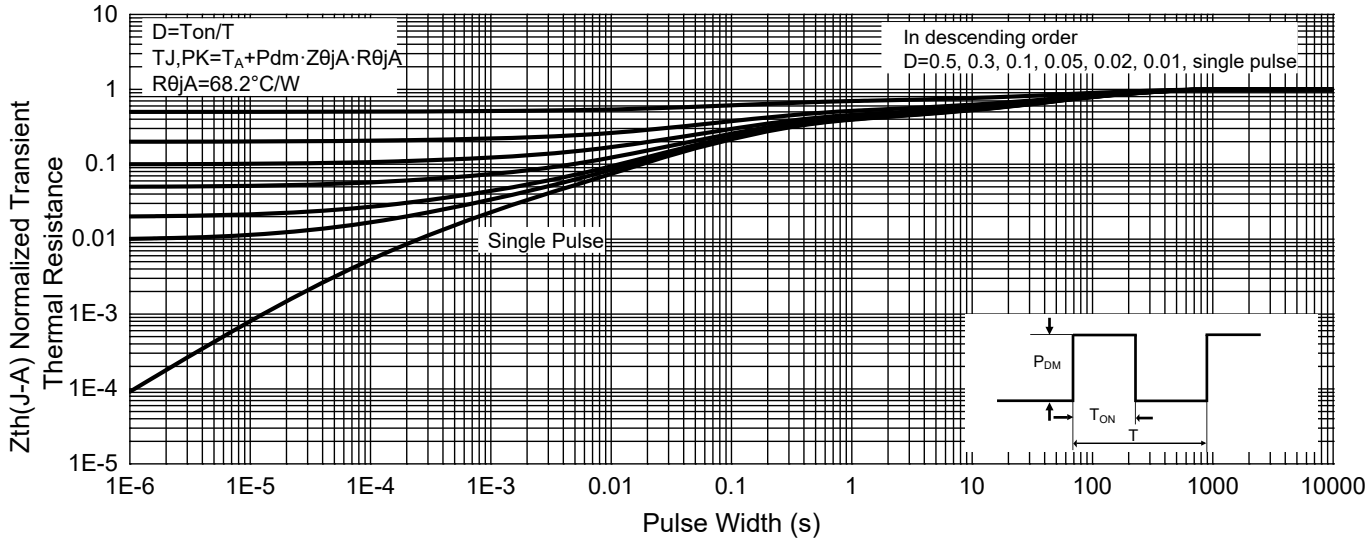


Fig. 13 -Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:3Kpcs/Reel

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